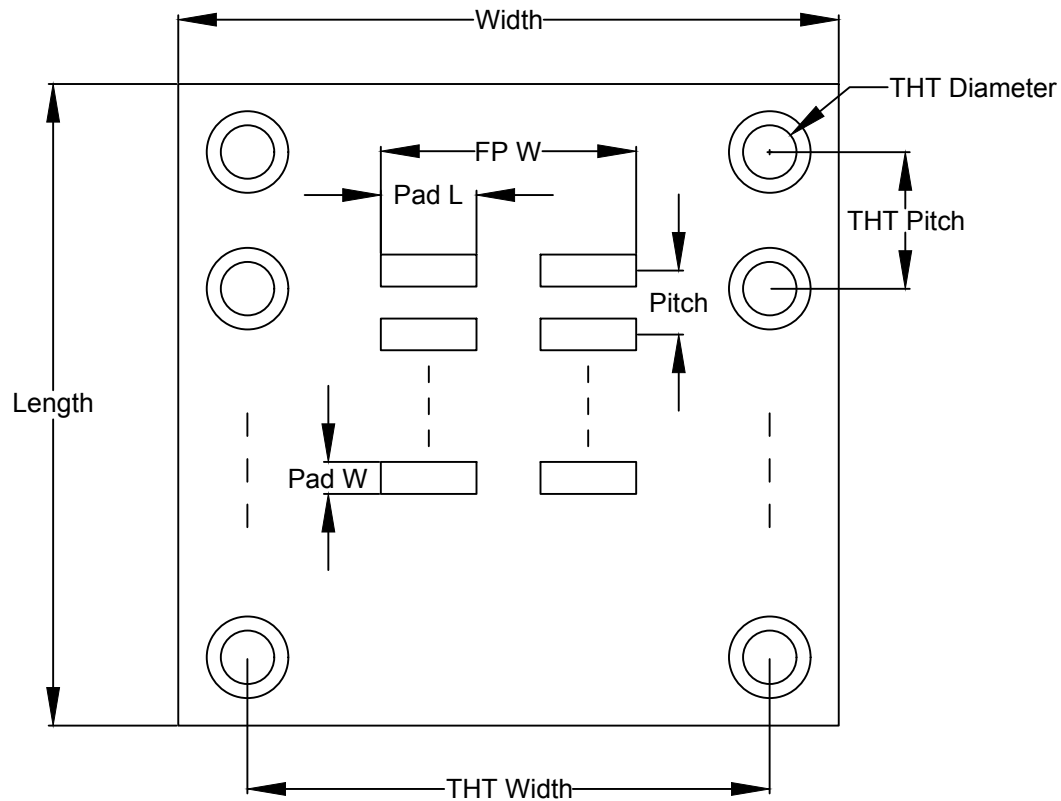


# Double-Sided SOIC/SOP/SSOP To DIP Breakout Board



(Not To Scale)

Board Dimensions						
Part #	Pin Count	Length (mm)	Width (mm)	THT Pitch (mm)	THT Diameter (mm)	THT Width (mm)
DE02008	8	11	12	2.54	1	7.6
DE02014	14	18.8	18.9	2.54	1	15.24
DE02016	16	21.4	18.9	2.54	1	15.24
DE02018	18	23.8	18.9	2.54	1	15.24
DE02020	20	26.3	18.9	2.54	1	15.24
DE02024	24	31.5	18.9	2.54	1	15.24
DE02028	28	36.8	18.9	2.54	1	15.24

Front Footprint				
Part #	Pitch (mm)	Pad W (mm)	Pad L (mm)	FP W (mm)
DE02008	1.27	0.6	4	9.2
DE02014	1.27	0.6	4	9.2
DE02016	1.27	0.6	4	9.2
DE02018	1.27	0.6	4	9.2
DE02020	1.27	0.6	4	9.2
DE02024	1.27	0.6	4	9.2
DE02028	1.27	0.6	4	9.2

Back Footprint				
Part #	Pitch (mm)	Pad W (mm)	Pad L (mm)	FP W (mm)
DE02008	0.65	0.35	4	9.2
DE02014	0.65	0.35	4	9.2
DE02016	0.65	0.35	4	9.2
DE02018	0.65	0.35	4	9.2
DE02020	0.65	0.35	4	9.2
DE02024	0.65	0.35	4	9.2
DE02028	0.65	0.35	4	9.2